

ABSTRACT

Disclosed are: an adhesive composition including an epoxy resin (A), an epoxy resin curing agent (B), a polyurethane resin (C), and an inorganic filler (D), in which the polyurethane resin (C) has a storage elastic modulus at 25°C, in a dynamic viscoelastic analysis, of 8.0 MPa or higher, a proportion of the polyurethane resin (C) based on a total content of the epoxy resin (A) and the polyurethane resin (C) is from 2.0 to 50.0 mass%, and a maximum tensile stress in a stress-strain curve when a tensile strength is applied to a film adhesive formed using the adhesive composition is 7.0 MPa or higher; a film adhesive using the adhesive composition; a semiconductor package; and a producing method thereof.

(Fig. 1)